TOSHIBA LED Lamps

TLRK1100C(T11), TLRMK1100C(T11), TLSK1100C(T11), TLOK1100C(T11), TLYK1100C(T11)

Panel Circuit Indicators

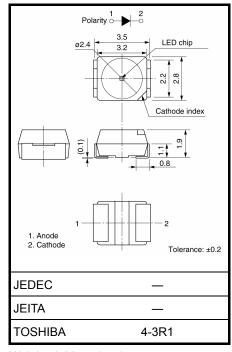
- Surface-mount devices
- 3.2 (L) mm × 2.8 (W) mm × 1.9 (H) mm
- Flat-top type
- InGaAlP LEDs
- High luminous intensity
- Low drive current, high-intensity light emission
- Colors: red, orange, yellow
- Applications: automotive use, message signboards, backlighting etc.
- Standard embossed tape packing: T11 (2000/reel)

8-mm tape reel

Color and Material

Part Number	Color	Material
TLRK1100C	Red	
TLRMK1100C	Red	
TLSK1100C	Red	InGaAℓP
TLOK1100C	Orange	
TLYK1100C	Yellow	

Unit: mm



Weight: 0.035 g (typ.)



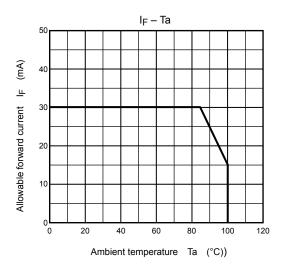
Absolute Maximum Ratings (Ta = 25°C)

Product Name	Forward Current I _F (mA) Please see Note 1	Reverse Voltage V _R (V)	Power Dissipation P _D (mW)	Operation Temperature T _{opr} (°C)	Storage Temperature T _{stg} (°C)
TLRK1100C					
TLRMK1100C					
TLSK1100C	30	4	75	-40 to 100	-40 to 100
TLOK1100C					
TLYK1100C					

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Forward current derating



Electrical Characteristics (Ta = 25°C)

Product Name	F	orward \	Reverse Current I _R			
	Min	Тур.	Max	lF	Max	V _R
TLRK1100C	1.8	2.1	2.5	20	10	
TLRMK1100C	1.8	2.1	2.5			4
TLSK1100C	1.8	2.1	2.5			
TLOK1100C	1.8	2.1	2.5			
TLYK1100C	1.8	2.2	2.5			
Unit		V		mA	μА	V



Optical Characteristics-1 (Ta = 25°C)

Product Name	L	uminous	Intensity I	Available Iv rank	
Product Name	Min	Тур.	Max	lF	Please see Note 2
TLRK1100C	100	300	500	20	RA/SA/TA
TLRMK1100C	160	400	800	20	SA / TA / UA
TLSK1100C	250	500	1250	20	TA / UA / VA
TLOK1100C	250	500	1250	20	TA / UA / VA
TLYK1100C	160	400	800	20	SA / TA / UA
Unit	mcd	mcd	mcd	mA	

Note 2: The specification on the above table is used for lv classification of LEDs in Toshiba facility.

Each reel includes the same rank LEDs. Let the delivery ratio of each rank be unquestioned.

Rank	Luminous Intensity IV			
	Min	Max		
RA	100	200		
SA	160	320		
TA	250	500		
UA	400	800		
VA	630	1250		
Unit	mcd	mcd		

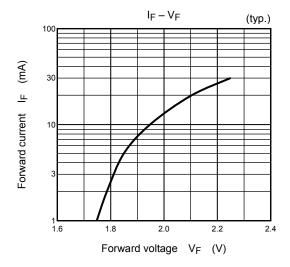
Optical Characteristics-2 (Ta = 25°C)

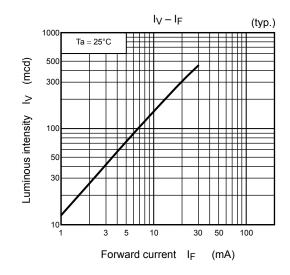
				Emission	Spectrum	1		
Product Name	Peak Emission Wavelength λ _p		Δλ	Domina	nt Wavel	ength λ _d	lF	
	Min	Тур.	Max	Тур.	Min	Тур.	Max	
TLRK1100C	_	644	_	14	624	630	638	
TLRMK1100C	_	636	_	14	620	626	634	
TLSK1100C	_	623	_	14	607	613	621	20
TLOK1100C	_	612	_	14	599	605	613	
TLYK1100C	_	592	_	13	583	590	595	
Unit		nm		nm		nm		mA

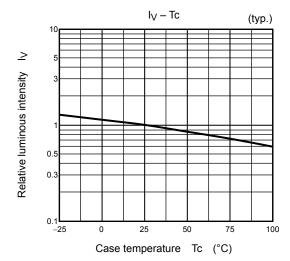
The cautions

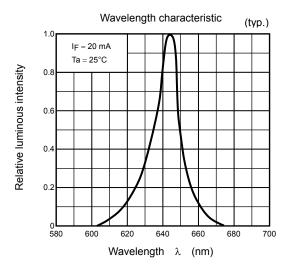
• This product is designed as a general display light source usage, and it has applied the measurement standard that matched with the sensitivity of human's eyes. Therefore, it is not intended for usage of functional application (ex. Light source for sensor, optical communication and etc) except general display light source.

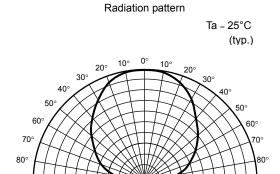
TLRK1100C









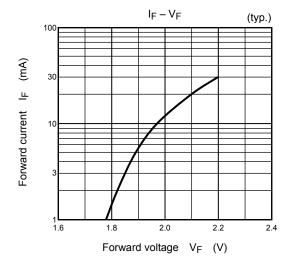


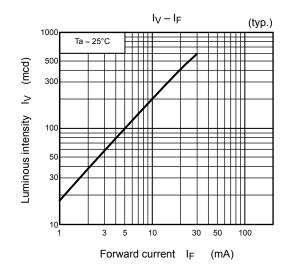
0.4 0.6

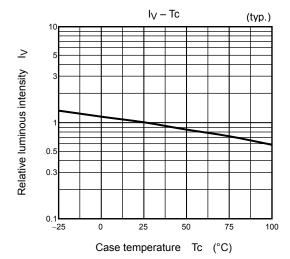
0.2

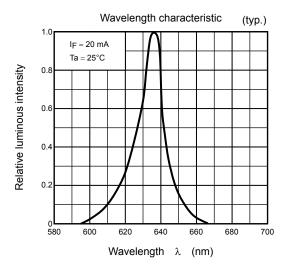
8.0

TLRMK1100C



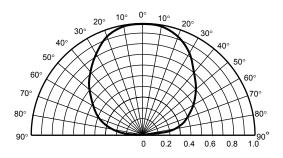




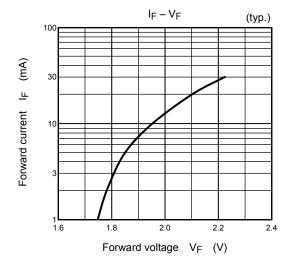


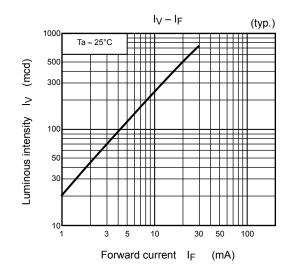
Radiation pattern

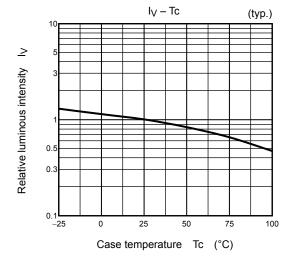
 $Ta = 25^{\circ}C$ (typ.)

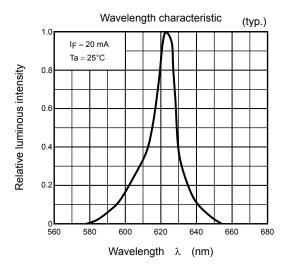


TLSK1100C



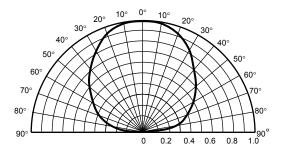




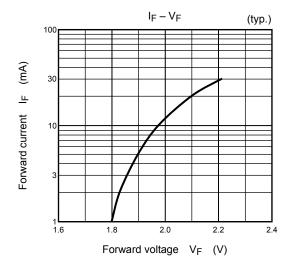


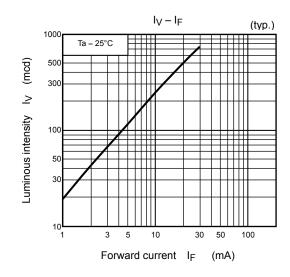
Radiation pattern

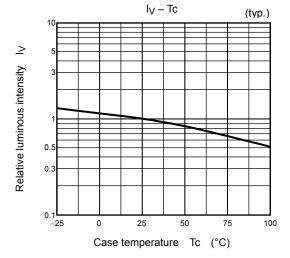
 $Ta = 25^{\circ}C$ (typ.)

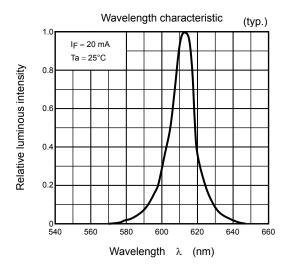


TLOK1100C





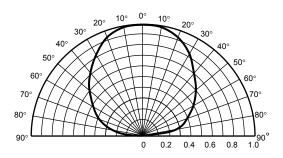




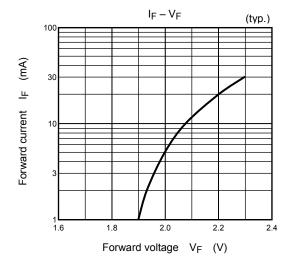
Radiation pattern

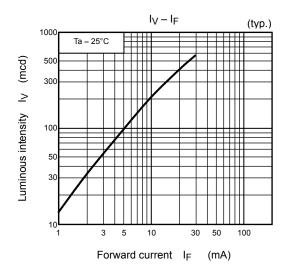
 $Ta = 25^{\circ}C$ (typ.)

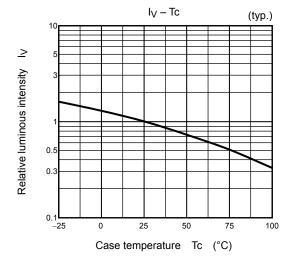
7

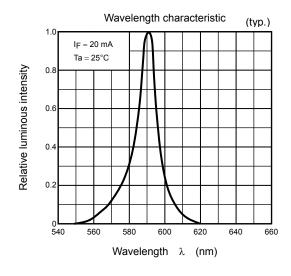


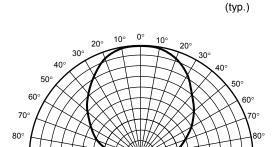
TLYK1100C











0.2 0.4 0.6

Radiation pattern

 $Ta = 25^{\circ}C$

Packaging

These LED devices are packed in an aluminum envelope with a silica gel and a moisture indicator to avoid moisture absorption. The optical characteristics of the devices may be affected by exposure to moisture in the air before soldering and they should therefore be stored under the following conditions:

1. This moisture proof bag may be stored unopened within 12 months at the following conditions. Temperature: 5° C to 30° C

Humidity: 90% (max)

- 2. After opening the moisture proof bag, the devices should be assembled within 168 hours in an environment of 5°C to 30°C/60% RH or below.
- 3. If upon opening, the moisture indicator card shows humidity 30% or above (Color of indication changes to pink) or the expiration date has passed, the devices should be baked in taping with reel.

After baking, use the baked devices within 72 hours, but perform baking only once.

Baking conditions: 60±5°C, for 12 to 24 hours.

- Expiration date: 12 months from sealing date, which is imprinted on the same side as this label affixed.
- 4. Repeated baking can cause the peeling strength of the taping to change, then leads to trouble in mounting. Furthermore, prevent the devices from being destructed against static electricity for baking of it.
- 5. If the packing material of laminate would be broken, the hermeticity would deteriorate. Therefore, do not throw or drop the packed devices.

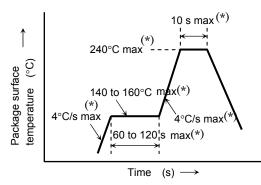
Mounting Method

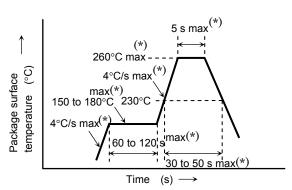
Soldering

• Reflow soldering (example)

Temperature profile for Pb soldering (example)

Temperature profile for Pb-free soldering (example)





- The products are evaluated using above reflow soldering conditions. No additional test is performed exceed the condition (i.e. the condition more than (*)MAX values) as a evaluation. Please perform reflow soldering under the above conditions.
- Please perform the first reflow soldering with reference to the above temperature profile and within 168 h of opening the package.
- Second reflow soldering

In case of second reflow soldering should be performed within 168 h of the first reflow under the above conditions.

Storage conditions before the second reflow soldering: 30°C, 60% RH (max)

• Make any necessary soldering corrections manually.

(only once at each soldering point)

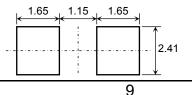
Soldering iron: 25 W

Temperature: 300°C or less Time: within 3 s

• If the products need to be performed by other soldering method (ex. wave soldering), please contact Toshiba sales representative.

Recommended soldering pattern

Unit: mm





Cleaning

When cleaning is required after soldering, Toshiba recommends the following cleaning solvents. It is confirmed that these solvents have no effect on semiconductor devices in our dipping test (under the recommended conditions). In selecting the one for your actual usage, please perform sufficient review on washing condition, using condition and etc.

ASAHI CLEAN AK-225AES: (made by ASAHI GLASS)

KAO CLEAN TROUGH 750H: (made by KAO)

PINE ALPHA ST-100S: (made by ARAKAWA CHEMICAL)

Precautions when Mounting

Do not apply force to the plastic part of the LED under high-temperature conditions.

To avoid damaging the LED plastic, do not apply friction using a hard material.

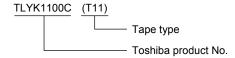
When installing the PCB in a product, ensure that the device does not come into contact with other emponents.

Tape Specifications

1. Product number format

The type of package used for shipment is denoted by a symbol suffix after the product number. The method of classification is as below. (this method, however does not apply to products whose electrical characteristics differ from standard Toshiba specifications)

- (1) Tape Type: T11 (4-mm pitch)
- (2) Example

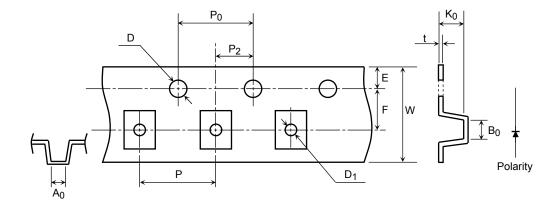


2. Tape dimensions

Unit: mm

Symbol	Dimension	Tolerance
D	1.5	+0.1/-0
E	1.75	±0.1
P ₀	4.0	±0.1
t	0.3	±0.05
F	3.5	±0.05
D ₁	1.5	±0.1

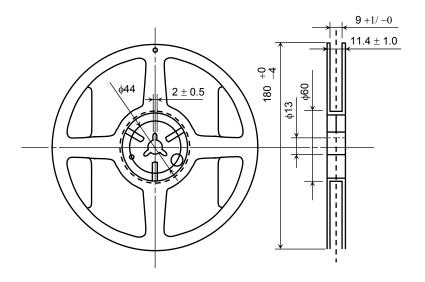
Symbol	Dimension	Tolerance
P ₂	2.0	±0.05
W	8.0	±0.3
Р	4.0	±0.1
A ₀	2.9	±0.1
B ₀	3.7	±0.1
K ₀	2.3	±0.1



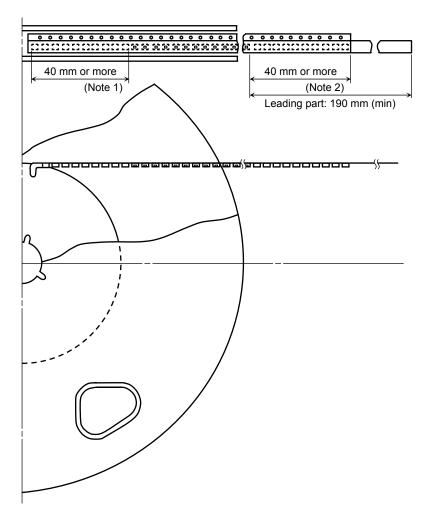
10

3. Reel dimensions

Unit: mm



4. Leader and trailer sections of tape



Note 1: Empty trailer section

Note 2: Empty leader section



5. Packing form

(1) Packing quantity

Reel	2,000 pcs
Carton	10,000 pcs

(2) Packing form: Each reel is sealed in an aluminum pack with silica gel.

6. Label format

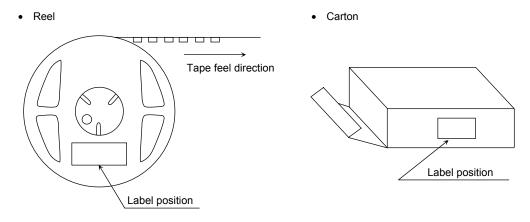
(1) Example: TLYK1100C (T11)

I	P/N:				TOSHIBA
	TYPE	TLYK1100C		_	
	ADDC	(T11)	Q'TY	2,000 pcs	
		ber Key code for TSB SYMBOL)	32C	2000	

Use under 5-30degC/60%RH within 168h



(2) Label location



 The aluminum package in which the reel is supplied also has the label attached to center of one side.

RESTRICTIONS ON PRODUCT USE

20070701-EN GENERAL

- The information contained herein is subject to change without notice.
- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.
 In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc.
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in his document shall be made at the customer's own risk.
- The products described in this document shall not be used or embedded to any downstream products of which manufacture, use and/or sale are prohibited under any applicable laws and regulations.
- GaAs(Gallium Arsenide) is used in this product. The dust or vapor is harmful to the human body. Do not break, cut, crush or dissolve chemically.
- Please contact your sales representative for product-by-product details in this document regarding RoHS
 compatibility. Please use these products in this document in compliance with all applicable laws and regulations
 that regulate the inclusion or use of controlled substances. Toshiba assumes no liability for damage or losses
 occurring as a result of noncompliance with applicable laws and regulations.